

200mA Low-Noise, High-PSRR Negative Output Low-Dropout Linear Regulators

FEATURES

- Ultralow Noise: 60μV_{RMS} Typical
- High PSRR: 65dB Typical at 1kHz
- Low Dropout Voltage: 280mV Typical at 200mA, 2.5V
- Available in –2.5V and Adjustable (–1.2V to –10V) Versions
- Stable With a 2.2µF Ceramic Output Capacitor
- Less Than 2µA Typical Quiescent Current in Shutdown Mode
- 2% Overall Accuracy (Line, Load, Temperature)
- Thermal and Over-Current Protection
- SOT23-5 (DBV) Package
- Operating Junction Temperature Range: -40°C to +125°C

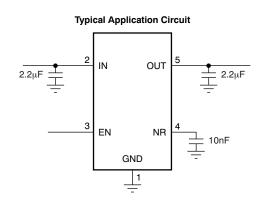
APPLICATIONS

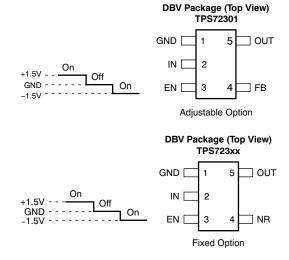
- Optical Drives
- Optical Networking
- Noise Sensitive Circuitry
- GaAs FET Gate Bias
- Video Amplifiers

DESCRIPTION

The TPS723xx family of low-dropout (LDO) negative voltage regulators offers an ideal combination of features to support low noise applications. These devices are capable of operating with input voltages from -10V to -2.7V, and support outputs from -10V to -1.2V. These regulators are stable with small, low-cost ceramic capacitors, and include enable (EN) and noise reduction (NR) functions. Thermal short-circuit and over-current protections are provided by internal detection and shutdown logic. High PSRR (65dB at 1kHz) and low noise (60µV $_{RMS}$) make the TPS723xx ideal for low-noise applications.

The TPS723xx uses a precision voltage reference to achieve 2% overall accuracy over load, line, and temperature variations. Available in a small SOT23-5 package, the TPS723xx family is fully specified over a temperature range of -40°C to +125°C.





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SLVS346B-SEPTEMBER 2003-REVISED JULY 2007





This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION(1)

PRODUCT	V _{OUT} ⁽²⁾
TPS723 <i>xxyyz</i>	XX is nominal output voltage (for example, 25 = 2.5V, 01 = Adjustable.) YYY is package designator. Z is package quantity.

- (1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Output voltages from -1.2V to -9V in 100mV increments are available. Minimum order quantities apply; contact factory for details and availability.

ABSOLUTE MAXIMUM RATINGS(1)(2)

Over operating temperature range, unless otherwise noted.

	VALUE	UNITS		
Input voltage range, V _{IN}	-11 to +0.3	V		
Noise reduction pin voltage range, V _{NR}	-11 to +5.5	V		
Enable voltage range, V _{EN}	-V _{IN} to +5.5	V		
Output voltage range, V _{OUT}	-11 to +0.3	V		
Output current, I _{OUT}	Internally limited			
Output short-circuit duration	Indefinite			
Continuous total power dissipation, P _D	See Power Dissipation Ra	atings table		
Junction temperature range, T _J	-55 to +150	°C		
Storage temperature range, T _{stg}	-65 to +150	°C		

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

POWER DISSIPATION RATINGS

BOARD	PACKAGE	R _{eJC}	$R_{ heta JA}$	DERATING FACTOR ABOVE T _A = +25°c	T _A ≤ +25°c POWER RATING	T _A = +70°c POWER RATING	T _A = +85°C POWER RATING
Low-K ⁽¹⁾	DBV	64°C/W	255°C/W	3.9mW/°C	390mW	215mW	155mW
High-K ⁽²⁾	DBV	64°C/W	180°C/W	5.6mW/°C	560mW	310mW	225mW

⁽¹⁾ The JEDEC Low-K (1s) board design used to derive this data was a 3 inch x 3 inch, two-layer board with 2-ounce copper traces on top of the board.

⁽²⁾ All voltage values are with respect to network ground terminal.

⁽²⁾ The JEDEC High-K (2s2p) board design used to derive this data was a 3 inch × 3 inch, multilayer board with 1-ounce internal power and ground planes and 2-ounce copper traces on the top and bottom of the board.



ELECTRICAL CHARACTERISTICS

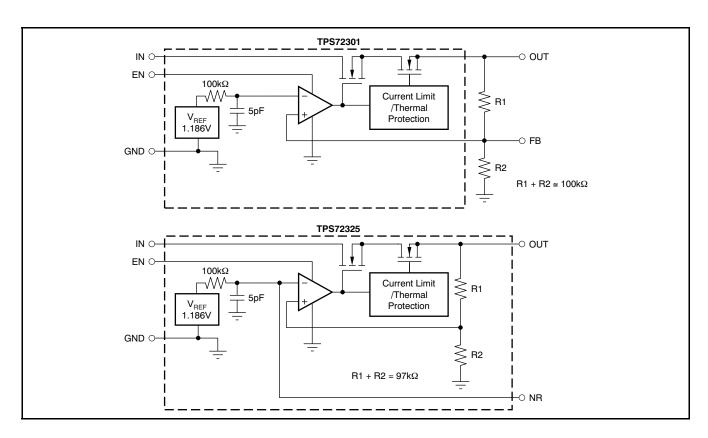
Over operating junction temperature range, $V_{IN} = V_{OUTnom} - 0.5V$, $I_{OUT} = 1mA$, $V_{EN} = 1.5V$, $C_{OUT} = 2.2\mu F$, and $C_{NR} = 0.01\mu F$, unless otherwise noted. Typical values are at $T_J = +25^{\circ}C$.

				TI				
	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNITS	
V _{IN}	Input voltage range ⁽¹⁾			-10		-2.7	V	
V_{FB}	Feedback reference voltage	TPS72301	T _J = +25°C	-1.210	-1.186	-1.162	V	
	Output voltage range	TPS72301		-10 + V _{DO}		V_{FB}	V	
		Nominal	T _J = +25°C	-1		1	%	
V _{OUT}	Accuracy	TPS72325 vs V _{IN} /I _{OUT} /T	$-10V \le V_{IN} \le V_{OUT} - 0.5V,$	-2	±1	2	%	
		TPS72301 vs V _{IN} /I _{OUT} /T	10μA ≤ I _{OUT} ≤ 200mA	-3	±1	3	%	
$V_{OUT}\%/V_{IN}$	Line regulation Load regulation		$-10V \le V_{IN} \le V_{OUT(nom)} - 0.5V$		0.04		%/V	
$V_{OUT}\%/I_{OUT}$	Load regulation		$0mA \le I_{OUT} \le 200mA$		0.002		%/mA	
V_{DO}	Dropout voltage at $V_{OUT} = 0.96 \times V_{OUT_{nom}}$	TPS72325	I _{OUT} = 200mA		280	500	mV	
I _{CL}	Current limit		$V_{OUT} = 0.85 \times V_{OUT(nom)}$	300	550	800	mA	
I	Ground pin current		$\begin{split} I_{OUT} &= 0 \text{mA } (I_Q), \\ -10 V &\leq V_{IN} \ \leq V_{OUT} - 0.5 V \end{split}$		130	200	μA	
I _{GND}	Ground pin current		$I_{OUT} = 200 \text{mA},$ -10V \le V _{IN} \le V _{OUT} - 0.5V	$V_{IN} \le V_{OUT} - 0.5V$				
I _{SHDN}	Shutdown ground pin current		$-0.4V \le V_{EN} \le 0.4V$, $-10V \le V_{IN} \le V_{OUT} - 0.5V$		0.1	2.0	μA	
I_{FB}	Feedback pin current		$-10V \le V_{IN} \le V_{OUT} - 0.5V$		0.05	1.0	μA	
PSRR	Decrease described in TD070005		$I_{OUT} = 200$ mA, 1kHz, $C_{IN} = C_{OUT} = 10$ µF		65		dB	
FORK	Power-supply rejection ratio	17372323	$I_{OUT} = 200$ mA, 10 kHz, $C_{IN} = C_{OUT} = 10$ µF	48			ив	
V _n	Output noise voltage	TPS72325	C_{OUT} = 10 μ F, 10Hz to 100kHz, I_{OUT} = 200mA		60		μV _{RMS}	
t _{STR}	Startup time		$V_{OUT} = -2.5V$, $C_{OUT} = 1\mu F$, $R_L = 25\Omega$		1		ms	
V _{EN(HI)}	Enable threshold positive			1.5			V	
V _{EN(LO)}	Enable threshold negative					-1.5	V	
V _{DIS(HI)}	Disable threshold positive					0.4	V	
V _{DIS(LO)}	Disable threshold negative			-0.4			V	
I _{EN}	Enable pin current		$-10V \le V_{IN} \le V_{OUT} - 0.5V,$ $-10V \le V_{EN} \le \pm 3.5V$		0.1	2.0	μA	
T	Thermal shutdown temperatu	····	Shutdown, temperature increasing		+165		°C	
T _{SD}	memai siiuluowii leiliperalu	ii G	Reset, temperature decreasing		+145			
T _J	Operating junction temperatu	re		-40		+125	°C	

⁽¹⁾ Maximum V_{IN} = $(V_{OUT} - V_{DO})$ or -2.7V, whichever is more negative.



FUNCTIONAL BLOCK DIAGRAM



TERMINAL FUNCTIONS

TERMINAL		
NAME	NO.	DESCRIPTION
GND	1	Ground
IN	2	Input supply
EN	3	Bipolar enable pin. Driving this pin above the positive enable threshold or below the negative enable threshold turns on the regulator. Driving this pin below the positive disable threshold and above the negative disable threshold puts the regulator into shutdown mode.
NR	4	Fixed voltage versions only. Connecting an external capacitor between this pin and ground, bypasses noise generated by the internal bandgap. This configuration allows output noise to be reduced to very low levels.
FB	4	Adjustable voltage version only. This pin is the input to the control loop error amplifier. It is used to set the output voltage of the device.
OUT	5	Regulated output voltage. A small 2.2µF ceramic capacitor is needed from this pin to GND to ensure stability.



TYPICAL CHARACTERISTICS

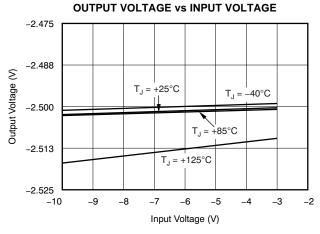


Figure 1.

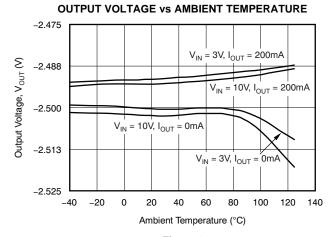


Figure 2.

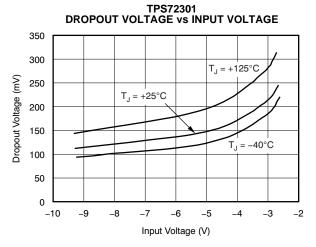


Figure 3.

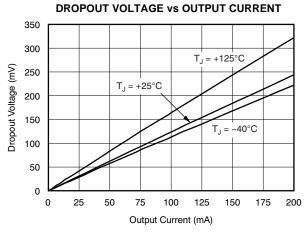


Figure 4.

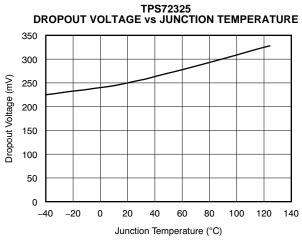


Figure 5.

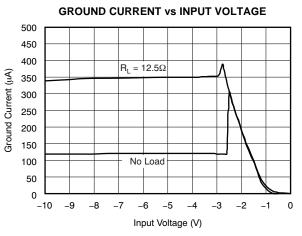


Figure 6.



TPS72325 at $V_{IN} = V_{OUTnom} - 0.5V$, $I_{OUT} = 1$ mA, $V_{EN} = 1.5V$, $C_{OUT} = 2.2\mu$ F, and $C_{NR} = 0.01\mu$ F, unless otherwise noted.

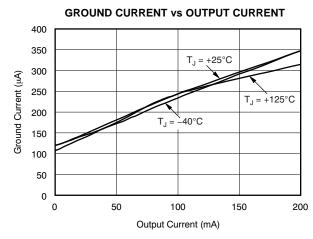


Figure 7.

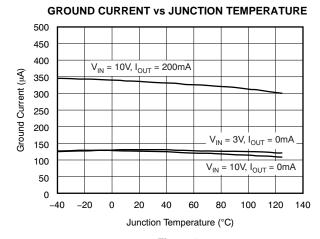


Figure 8.

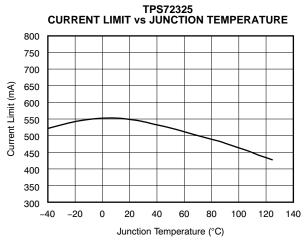


Figure 9.

TPS72301

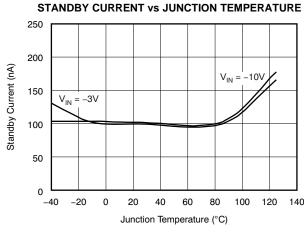


Figure 10.

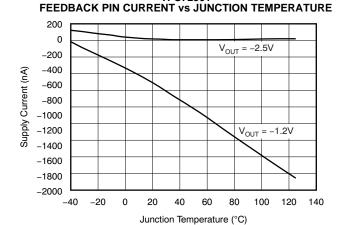


Figure 11.

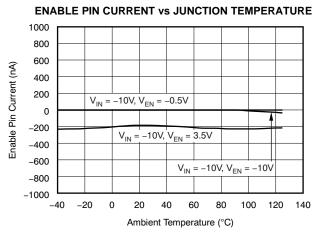


Figure 12.



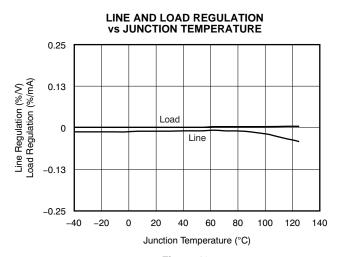


Figure 13.

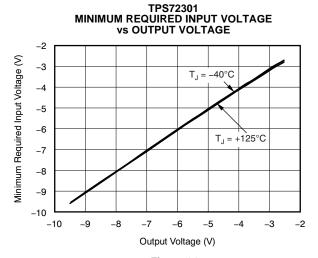


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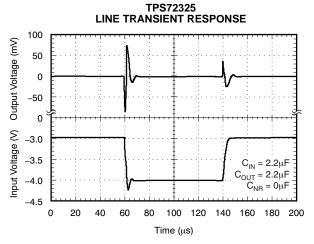


Figure 15.

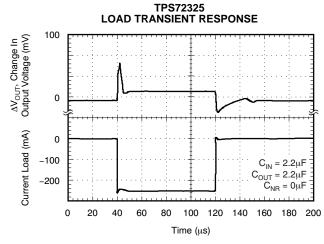


Figure 16.

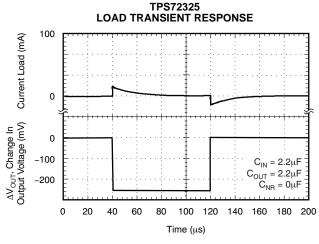


Figure 17.

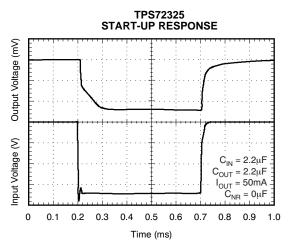


Figure 18.



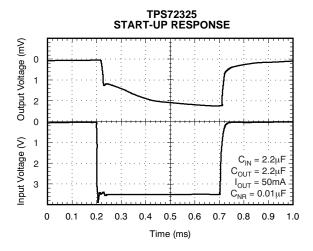


Figure 19.

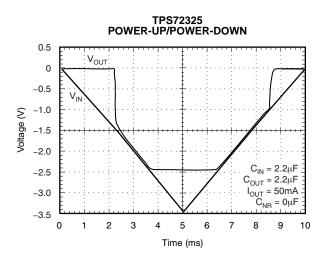


Figure 20.

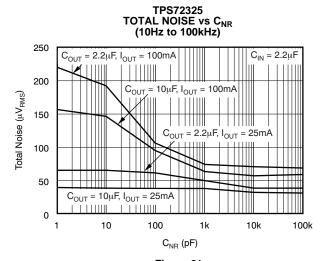


Figure 21.

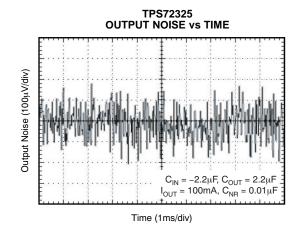


Figure 22.

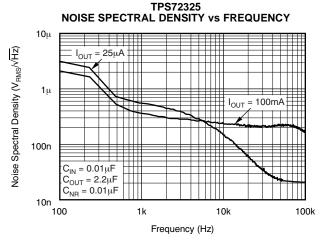


Figure 23.

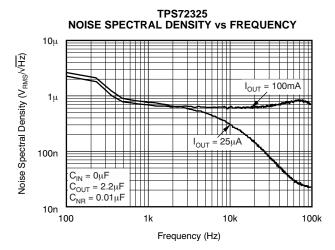
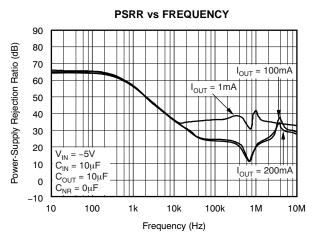


Figure 24.







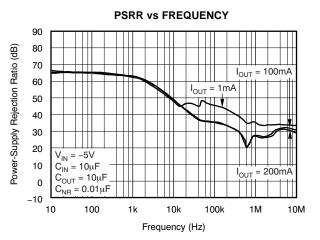


Figure 26.

APPLICATION INFORMATION

DEVICE OPERATION

The TPS723xx is a low-dropout negative linear voltage regulator with a rated current of 200mA. It is offered in trimmed output voltages between -1.5V and -5.2V and as an adjustable regulator from -1.2V to -10V. It features very low noise and high power-supply rejection ratio (PSRR), making it ideal for high-sensitivity analog and RF applications. A shutdown mode is available, reducing ground current to 2µA maximum over temperature and process. The TPS723xx is offered in a small SOT23 package and is specified over a -40°C to +125°C junction temperature range.

ENABLE

The enable pin is active above +1.5V and below -1.5V, allowing it to be controlled by a standard TTL signal or by connection to V_I if not used. When driven to GND most internal circuitry is turned off, putting the TPS723xx into shutdown mode, drawing $2\mu A$ maximum ground current.

ADJUSTABLE VOLTAGE APPLICATIONS

The TPS72301 allows designers to specify any output voltage from -10V to -1.2V. As shown in the application circuit in Figure 27, an external resistor divider is used to scale the output voltage (V_{OUT}) to the reference voltage. For best accuracy, use precision resistors for R1 and R2. Use the equations in Figure 27 to determine the values for the resistor divider.

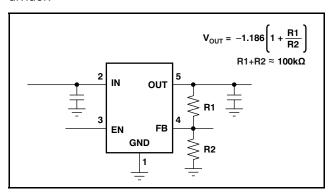


Figure 27. TPS72301 Adjustable LDO Regulator Programming

CAPACITOR SELECTION FOR STABILITY

Appropriate input and output capacitors should be used for the intended application. The TPS723xx only requires a 2.2µF ceramic output capacitor to be

used for stable operation. Both the capacitor value and ESR affect stability, output noise, PSRR, and transient response. For typical applications, a 2.2µF ceramic output capacitor located close to the regulator is sufficient.

OUTPUT NOISE

Without external bypassing, output noise of the TPS723xx from 10Hz to 100kHz is $200\mu V_{RMS}$ typical. The dominant contributor to output noise is the internal bandgap reference. Adding an external $0.01\mu F$ capacitor to ground reduces noise to $60\mu V_{RMS}.$ Best noise performance is achieved using appropriate low ESR capacitors for bypassing noise at the NR and OUT pins. See Figure 21 in the Typical Characteristics section.

POWER-SUPPLY REJECTION

The TPS723xx offers a very high PSRR for applications with noisy input sources or highly sensitive output supply lines. For best PSRR, use high-quality input and output capacitors.

CURRENT LIMIT

The TPS723xx has internal circuitry that monitors and limits output current to protect the regulator from damage under all load conditions. When output current reaches the output current limit (550mA typical), protection circuitry turns on, reducing output voltage to ensure that current does not increase. See Figure 9 in the Typical Characteristics section.

Do not drive the output more than 0.3V above the input. Doing so will bias the body diode in the pass FET, allowing current to flow from the output to the input. This current is not limited by the device. If this condition is expected, care should be taken to externally limit the reverse current.

THERMAL PROTECTION

As protection from damage due to excessive junction temperatures, the TPS723xx has internal protection circuitry. When junction temperature reaches approximately +165°C, the output device is turned off. After the device has cooled by about 20°C, the output device is enabled, allowing normal operation. For reliable operation, design is for worst-case junction temperature of \leq +125°C taking into account worst-case ambient temperature and load conditions.





11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
TPS72301DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	T08I	Samples
TPS72301DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	T08I	Samples
TPS72301DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	T08I	Samples
TPS72301DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	T08I	Samples
TPS72325DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	T02I	Samples
TPS72325DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	T02I	Samples
TPS72325DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	T02I	Samples
TPS72325DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	T02I	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

11-Apr-2013

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TPS72301, TPS72325:

Automotive: TPS72301-Q1, TPS72325-Q1

NOTE: Qualified Version Definitions:

Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

www.ti.com 26-Jan-2013

TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All differsions are norminal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS72301DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS72301DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS72325DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS72325DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

www.ti.com 26-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS72301DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS72301DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TPS72325DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS72325DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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